 3-State Buffer-Type Outputs Drive Bus Lines Directly 		R NT PACKA FOP VIEW)	AGE
 Bus-Structured Pinout 		$1 \cup 24$	Vcc
 Provides Extra Bus-Driving Latches 	1D []2		
Necessary for Wider Address/Data Paths or	2D 🛛	3 22	2Q
Buses With Parity	3D 🛛	4 21	3Q
 Buffered Control Inputs to Reduce 	4D [[5	5 20	4Q
dc Loading Effects	5D [6	6 19	5Q
• Power-Up High-Impedance State	6D [7	- P	
Package Options Include Plastic	7D [] 8	E	7Q
Small-Outline (DW) Packages and Standard	8D 🛛 9	9 16	8Q
Plastic (NT) 300-mil DIPs	<u> </u>	P	
		E	PRE
description	GND []1	12 13	LE

This 9-bit bus-interface D-type latch features

3-state outputs designed specifically for driving

highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The nine latches are transparent D-type latches with noninverting data (D) inputs.

A buffered output-enable (OE) input places the nine outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect the internal operation of the latches. Previously stored data can be retained or new data can be entered while the outputs are off.

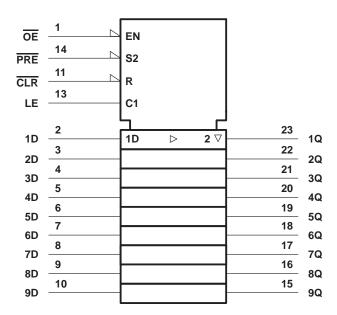
The SN74ALS843 is characterized for operation from 0°C to 70°C.

		FUNCT	ION TAE	BLE	
		INPUTS			OUTPUT
PRE	CLR	OE	LE	D	Q
L	Х	L	Х	Х	Н
Н	L	L	Х	Х	L
Н	н	L	Н	L	L
Н	н	L	н	Н	н
Н	н	L	L	Х	Q ₀
Х	Х	Н	Х	Х	Z

SN74ALS843 9-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS

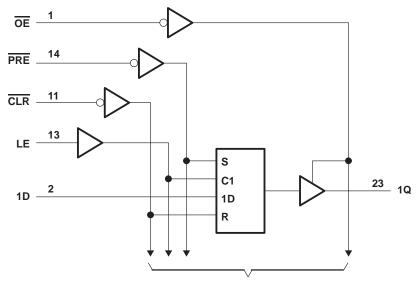
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Eight Other Channels



SN74ALS843 9-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS SDAS232A – DECEMBER 1983 – REVISED JANUARY 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}	
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	V
VIH	High-level input voltage		2			V
VIL	Low-level input voltage				0.8	V
IOH	High-level output current				-2.6	mA
I _{OL}	Low-level output current				24	mA
	Pulse duration CLR or PRE low LE high	CLR or PRE low	35			ns
tw		20			115	
t _{su}	Setup time, data before LE \downarrow		10			ns
t _h	Hold time, data after LE \downarrow		5			ns
Т _А	Operating free-air temperature		0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST COND	MIN T	YP‡	MAX	UNIT	
VIK	V _{CC} = 4.5 V,	lj = – 18 mA			-1.2	V
Varia	$V_{CC} = 4.5 V$ to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			V
VOH	$V_{CC} = 4.5 V,$	$I_{OH} = -2.6 \text{ mA}$	2.4	3.2		v
		I _{OL} = 12 mA		0.25	0.4	V
VOL	$V_{CC} = 4.5 V$	I _{OL} = 24 mA		0.35	0.5	v
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			20	μΑ
IOZL	V _{CC} = 5.5 V,	V _O = 0.4 V			-20	μA
li li	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.1	mA
ЦΗ	V _{CC} = 5.5 V,	VI = 2.7 V			20	μΑ
ΙIL	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1	mA
١ _O §	V _{CC} = 5.5 V,	V _O = 2.25 V	-30	-	-112	mA
		Outputs high		21	36	
Icc	$V_{CC} = 5.5 V$	Outputs low		41	67	mA
		Outputs disabled		25	42	

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5$ $C_L = 50 \text{ pF}$ $R1 = 500 \Omega$ $R2 = 500 \Omega$ $T_A = MIN \text{ to}$	UNIT	
			MIN	MAX	
^t PLH	D		2	13	
^t PHL	d	Q	4	18	ns
^t PLH	LE		5	21	
^t PHL	LL	Q	8	26	ns
^t PLH	PRE		5	22	ns
^t PHL	CLR	Q	6	23	115
^t PZH	OE		2	12	
tPZL	OE	Q	4	14	ns
^t PHZ	ŌĒ	0	2	10	
tPLZ	0E	Q	2	12	ns

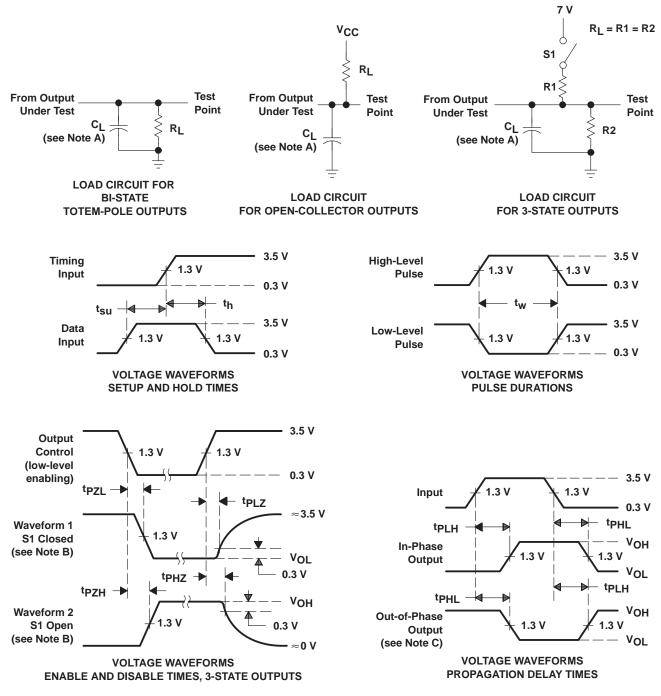
[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_r = t_f = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74ALS843DW	Obsolete	Production	SOIC (DW) 24	-	-	Call TI	Call TI	0 to 70	ALS843
SN74ALS843DWR	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS843

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*	All dimensions are nominal												
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74ALS843DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1



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PACKAGE MATERIALS INFORMATION

16-Apr-2024



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS843DWR	SOIC	DW	24	2000	350.0	350.0	43.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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